ECO SOLDER

Solder Paste JPP

Thermal Curing with Reflow for Reducing Number of Processes

Features

- Cures in reflow process and reduces the number of processes
- Has a low melting point and can be used for boards and components with low heat resistance
- Can be stored in a refrigerator

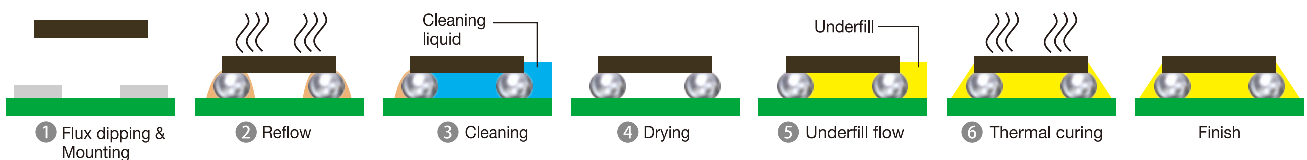
Revolutionary Products

L20-JPP unlimited expansion of the range of applications

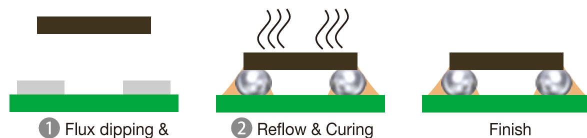
Product of high strength with a low melting point, realizes layered mounting and contributes to cost reduction

Reduced cleaning, curing and underfill flow processes

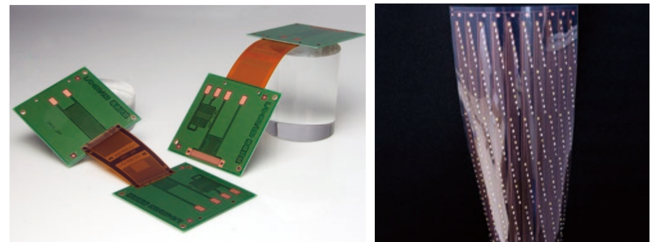
Normal flux



Joint protect flux (No Underfill)

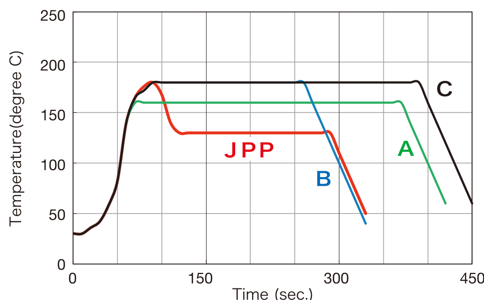


Without Cleaning, Baking & Underfill !!
(Under development)

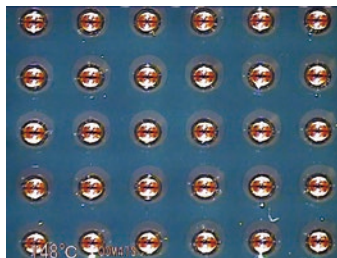


L20-JPP has a low melting point and applicable for low-priced boards and components with low heat resistance

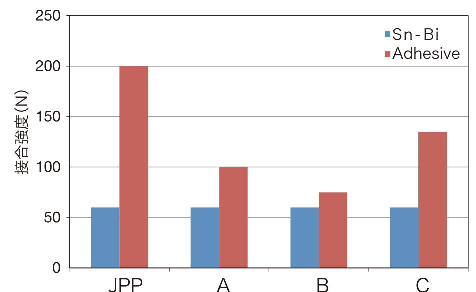
L20-JPP is cured in short time at a low temperature, achieves high productivity



Ensures sufficient wettability even through air reflow



L20-JPP has a high joint strength



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